THICK FILM CHIP RESISTOR ARRAYS

- CN SERIES -

FEATURES

- Small size and light weight, high density
- Reduction of assembly costs and matching with placement machines (automatic lacement)
- Powers per Element: 62.5mW or 1/16Watt
- Reliability, high quality
- Suitable for IR reflow soldering
- Convex

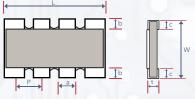


APPLICATIONS

- Entertainment
- Computer & Related Products
- Communication Equipment
- Power Equipment
- Measuring Equipment

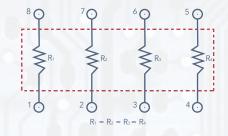


DIMENSIONS



UN									
TYPE	L W		t P		а	b	С		
CN22	1.0±0.1	1.0±0.1	0.35±0.1	0.65±0.05	0.3±0.1	0.15±0.1	0.25±0.2		
CN24	2.0±0.1	1.0±0.1	0.4±0.2	0.5±0.05	0.3±0.1	0.15±0.1	0.25±0.2		
CN34	3.2±0.1	1.6±0.15	0.55±0.1	0.8±0.5	0.45±0.1	0.3±0.2	0.3±0.2		

CONSTRUCTION OVER COAT GLASS RESISTIVE ELEMENTS CONDUCTOR CONVEX TERMINATION ALUMINA CERAMIC SUBSTRATE

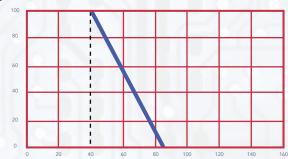


PART NUMBER GUIDE





DERATIVE CURVE



The reistors operated in ambient temperatures above 70°C, power rating must be derated in accordance with curve above.

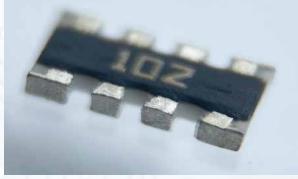
RATED VOLTAGE

The value of rated voltage shall be determined from formula (1).

 $E = \sqrt{P \times R(1)}$

E = Rated Voltage (V)P - Power Rating (W)

 $R = Nominal Resistance (\Omega)$







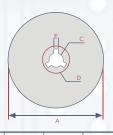


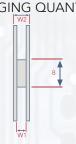
FEATURES

ITEM	SPECIFICATIONS	TEST METHODS				
Temperature Coefficient TCR: ±200ppm		Inspection Temp. Cold: +25°C~-55°C Hot: +25°C~+125°C				
Short Time Overload	±(2%+0.05Ω)	Apply 2.5 x rated voltage for 5 sec. Wait 30 minutes Measure resistance value				
Load Life $\pm (3\% + 0.05\Omega)$		1. Dwell in chamber at 70±2°C for ON:90 min. at rated voltage; then off: 30 min. 2. Perform 1,000 hours cyclically				
Load Life in Humidity $\pm (3\%+0.05\Omega)$		1. Dwell in humidity chamber at 40±2°C and 95% RH for ON:90 min. at rated voltage; then off: 30 min. 2. Perform 1,000 hours cyclically				
Temperature Cycling $\pm (1\%+0.05\Omega)$		155±3°C, make 5 cycles 2. Released 1 hour in room temp., then measure value.				
Effect of Soldering $\pm (2.5\% + 0.05\Omega)$ - Non-damage by machinery		Inmmersed in molten solder at 270±5°C for 10±.01 sec. Released 1 hour in room temp., then measure value.				
Solderability	95% coverage min.	In Immersed in rosin solution for 5~10 seconds. Re-immersed in solder pot at 230±5°C for 3±0.5 sec				
Intermittent Overload	±(5%+0.1Ω)	perform 10,000 voltage cycles as follows: ON (2.5 x rated voltage or current) 1 sec. and OFF 25 sec. Released 30 min without loading Measure resistance				
Dielectric Withstanding Voltage	No evidence of mechanical damage	Apply 300VAC for 1 second				
Insulation Resistance	10 Ω min	Apply 100VDC				

PACKAGING

REEL SPECIFICATIONS & PACKAGING QUANTITY



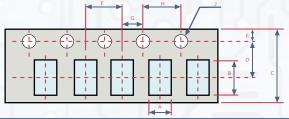


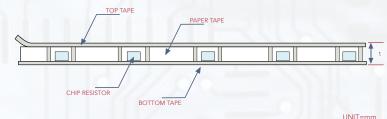


TYPE	А	В	С	D	Е	W1	W2
CN22	Ø178±2.0	Ø80±2.0	Ø13±0.5	Ø21.0	2.0±0.5	9.0±1.0	11.4±2.0
CN24	Ø178±2.0	Ø80±2.0	Ø13±0.5	Ø21.0	2.0±0.5	10.0±1.0	12.5±1.0
CN34	Ø178±2.0	Ø80±2.0	Ø13±0.5	Ø21.0	2.0±0.5	10.0±1.0	12.5±1.0

The top fixed tape for each carrier shall have an adhesion peel strength of 10 to 50G, measure method is shown above to peel away.

TAPING SPECIFICATION





TYPE		Α	В	С	D	Е	F	G	Н	J	t
CN22	10000	2.0±0.15	2.4±0.2	8.0±0.2	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.05	4.0±0.1	.5±0.1/0	.84±0.01
CN24	10000	2.0±0.15	2.4±0.2	8.0±0.2	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.05	4.0±0.1	.5±0.1/0	.84±0.01
CN34	5000	2.0±0.2	3.6±0.2	8.0±0.1	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.05	4.0±0.1	1.5±0.1	1.0



